Belongs to Document: VA06E05

6. Feb. 2013

SEMI

MEU Mktg / Eng Dr. P. Stelmaszyk

## PRODUCT/PROCESS CHANGE NOTIFICATION

TO: ME-UK: AR

CC:

ME-Italy: PA, BE ME-France: BA

ME-CE: MEA

MA, PM, RJ, YK, BK, BU, ST, JN, TGH, SR,

DC, IL, JL, SB, HE, MG

PCN number:

PCN-H-01-13

Herewith we want to	inform you	about the	following:
a) Product change:			8

Process change:

 $\boxtimes$ 

SiRF devices: RAxxx modules and RDxxx b) Old Mitsubishi type number: transistors. A detailed part number list is

attached. No change.

Not applicable

c) New Mitsubishi type number:

d) Expected last order and shipment dates for unchanged devices to be supplied:

e) Expected first shipment date of changed devices:

f) Manufacturing location and product line affected:

g) Description of the proposed change:

h) Comparison table of change attached:

i) Reliability and/or engineering test data are:

j) Customer spec. / part number:

April 2013 (ex-works)

Shimane Masuda Electronics, Isahaya Electronics

DATE:

FROM:

DEPT .:

Change Gold Bonding Wire supplier. Now: Sumitomo Metal Mining. Future: Tanaka Electronics.

Yes ⊠ No □

attached:

available on request:

all included

(Signature of Mgr HF/OPTO Marketing/ Engineering)

Note: Please comment until 6. March 2013. Otherwise we regard the PCN as accepted.

F-NO: PCN-H-01-13.DOC

Revision:

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